IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mfg	Informati	ion	
Supplier Inform	mation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2025-07-04			
Contact Name		Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-Env-Stew	vards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com				
authorized Repres	sentative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	r Item Number Mfr Iter		Item Number Mfr Item Name			Effective Dat	e Version	Version Manufacturing		ng Site	Weight*		UOM	Unit Type
		74LCX244MTCX		LV Buffer/Line Driver			2025-07-04		F	PH4		73	.596	mg	Each
Tanufacturing	g Proccess Informati	ion		,				, ,							
Termina	l Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	020 MSL Rating		Peak Process Body Temperature		e Max Time at Peak Temper		Temperatur	ture Number of Reflow Cycles		eles
Preciou Sn)	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		C 30			seconds	ds 3		
Comments															
vel 1 - maximum	time at peak temperatur	e during so	ldering is 10-3	30 seconds											
or more informat	tion regarding material c	omposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.25	mg	Supplier	Silicon (Si)	7440-21-3		1.25	mg
Die Attach	0.136	mg		Bismaleimide Resin	proprietary data		0.0224	mg
			Supplier	Other Additive Agents	Proprietary Data		0.0048	mg
			Supplier	Silver (Ag)	7440-22-4		0.1088	mg
Lead Frame	30.624	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0459	mg
			Supplier	Silicon (Si)	7440-21-3		0.1991	mg
			В	Nickel (Ni)	7440-02-0		0.9187	mg
			Supplier	Copper (Cu)	7440-50-8		29.4603	mg
Mold Compound-Black	40.867			Epoxy resin	proprietary data		3.8824	mg
			Supplier	Phenol Resin	Proprietary Data		2.0433	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2043	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.7369	mg
Plating	0.223		Supplier	Palladium (Pd)	7440-05-3		0.006	mg
			В	Nickel (Ni)	7440-02-0		0.213	mg
			Supplier	Gold (Au)	7440-57-5		0.004	mg
Wire Bond - Au	0.496	mg	Supplier	Gold (Au)	7440-57-5		0.496	mg